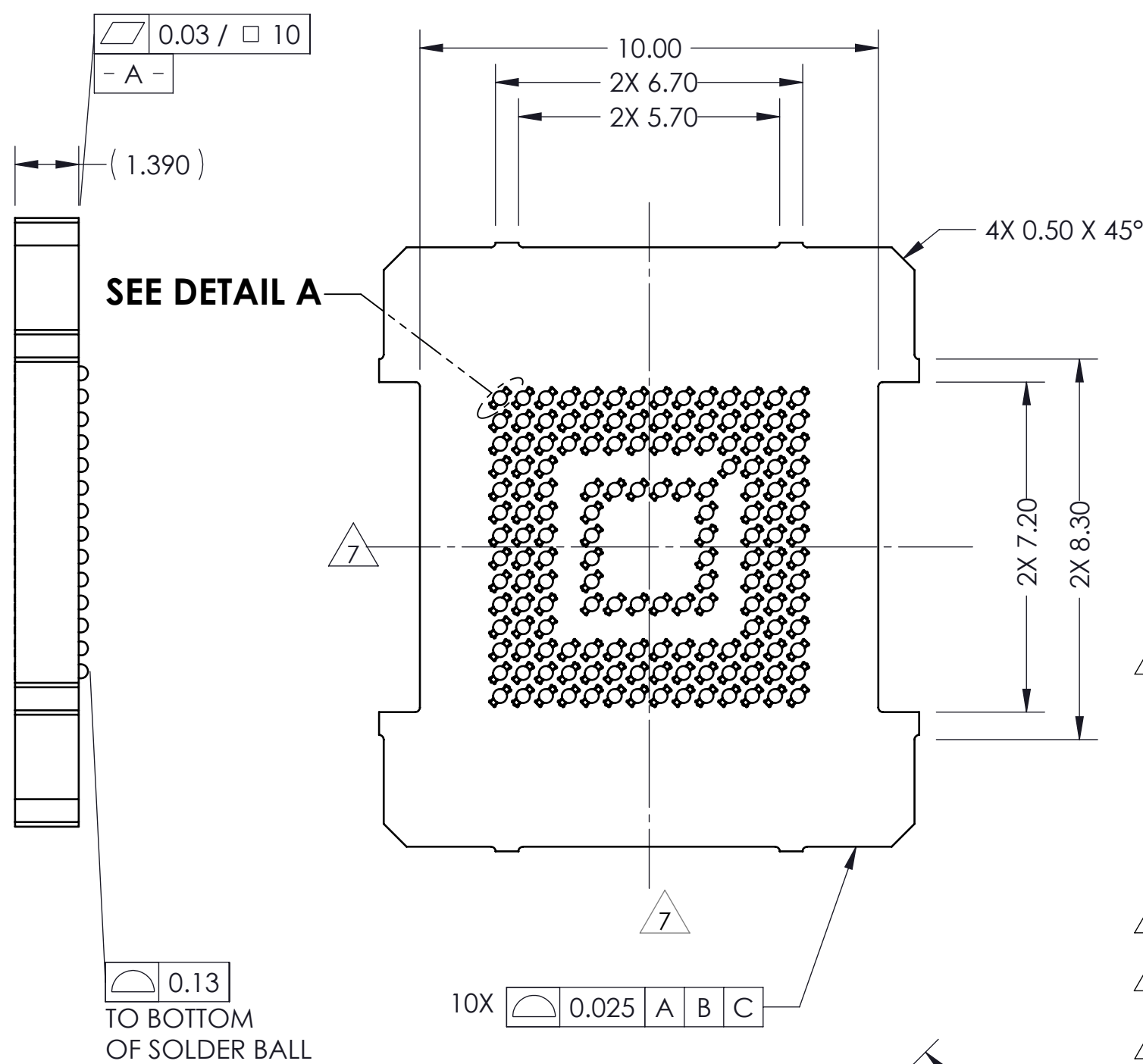
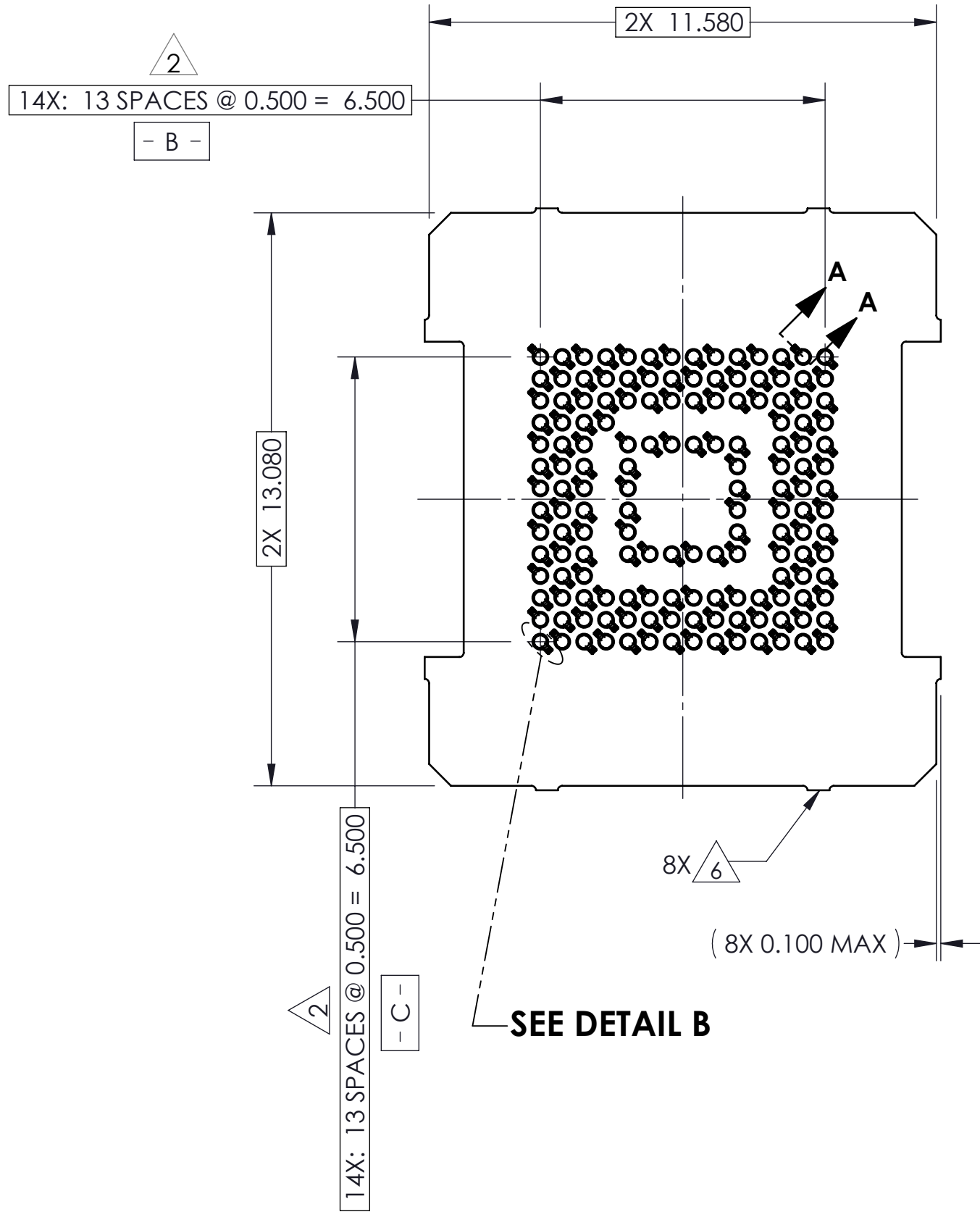
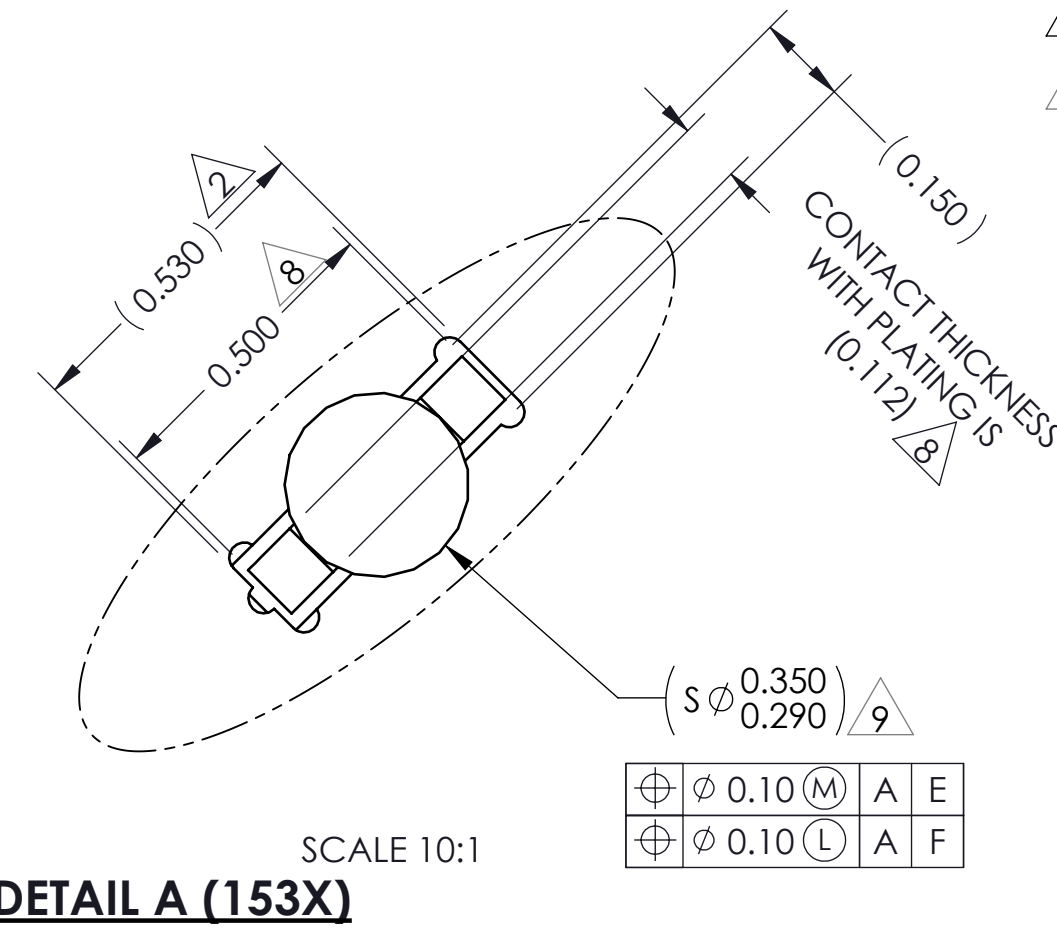
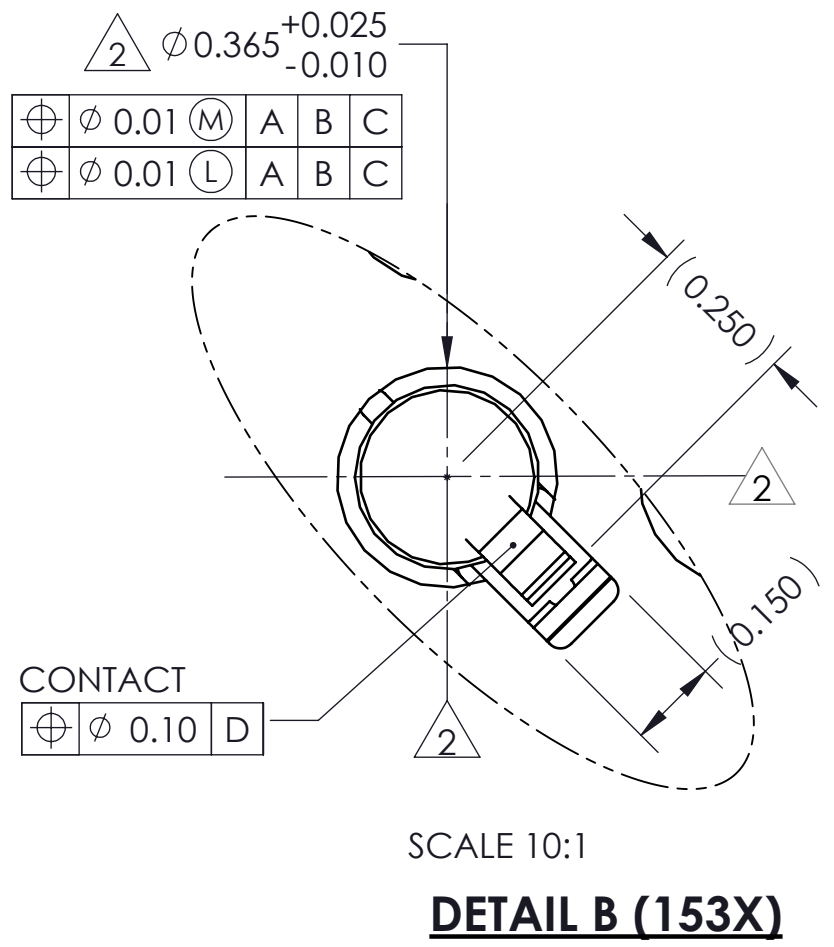
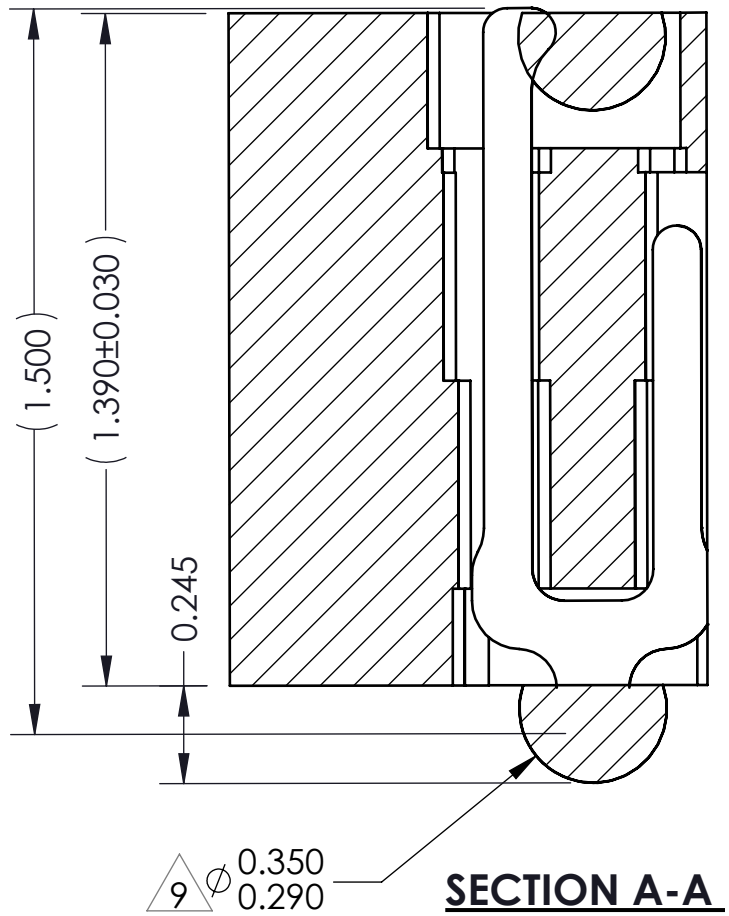


REV	ECO	BY	DESCRIPTION	APV	DATE
A	31309	MP	Initial Design	MP	06/14/13
B	32096	RS	Updated Socket Solder Ball Size	NSJ	08/22/19



- Notes:
- Reference HSI0 Technologies specification 103862-0004 for solder attachment.
  - Dimension locates center of contact/ slot.
  - Reference HSI0 Technologies specification 103863-0001 for application notes.
  - Footprint part number is 104311-0291.
  - Datums **- B -** and **- C -** are determined by  $\phi 0.365$  features on corner slots.
  - Tooling marks permitted. Maximum 0.10 protrusion (shown).
  - E -** Center of ball pattern.
  - F -** Center of contact.
  - Eutectic solder balls.

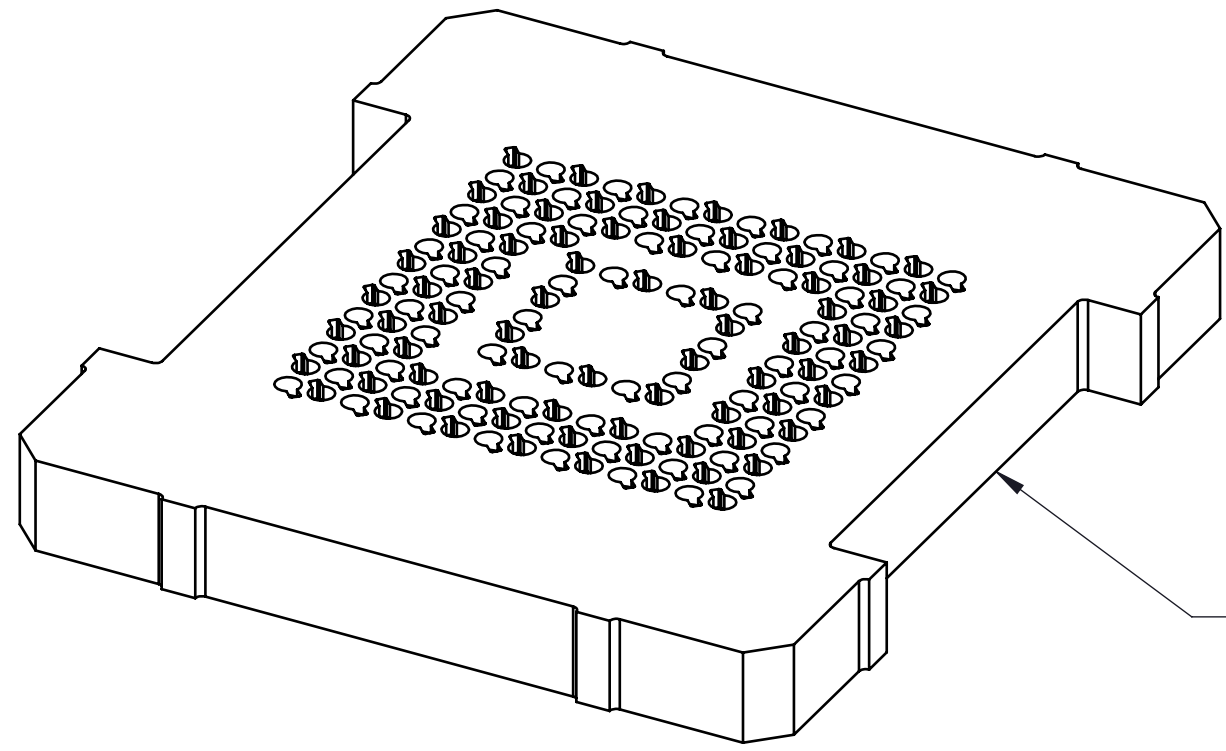


Parts List	
Part Number	Description
107248-0026	CS, 153G4011.5X13-0.50
103864-0128	PRESS, DEVICE INSERT, GRYP 11.5 X 13 (SOLD SEPARATELY)
105900-0004	EXTRACTION TOOL, 4 X 53 (SOLD SEPARATELY)
104553-0220	STEN FLEX, 153G4011.5X13-0.50 (SOLD SEPARATELY)
108639-0003	ALIGNMENT FRAME, G40, 11.5X13.0 (SOLD SEPARATELY)

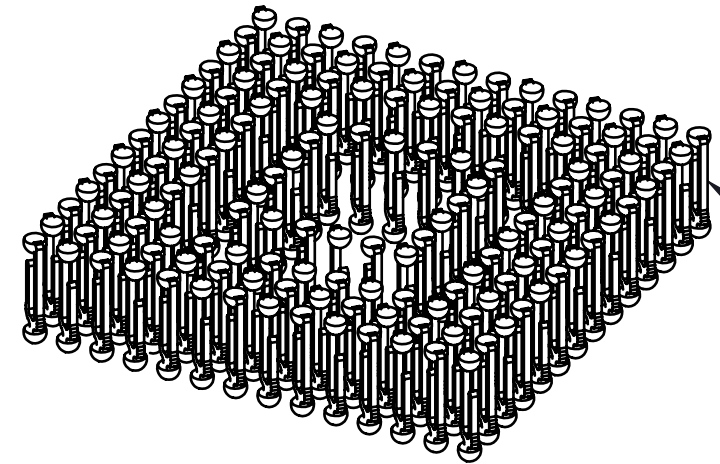
<p><b>HSIO technologies</b> PROPRIETARY AND CONFIDENTIAL</p> <p>THE INFORMATION CONTAINED IN THIS DRAWING IS THE SOLE PROPERTY OF HSI0 TECHNOLOGIES, LLC. ANY REPRODUCTION IN PART OR AS A WHOLE WITHOUT THE WRITTEN PERMISSION OF HSI0 TECHNOLOGIES, LLC IS PROHIBITED.</p>	UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ANGULAR: ± 1° X.X ± 0.25 X.XX ± 0.10 X.XXX ± 0.050	NAME MP DATE 11/28/2019	<b>HSIO TECHNOLOGIES, LLC.</b> 13300 67th AVENUE NORTH MAPLE GROVE, MINNESOTA 55311 763-447-6260	
	INTERPRET GEOMETRIC TOLERANCING PER:	CHECKED MP 06/14/13		TITLE: SCKT, 153G4011.5X13-0.50 WITH EUTECTIC SOLDER BALLS
	MATERIAL SEE BOM	LEGEND: △ NOTE CALLOUT □ REVISION CHANGE ○ ITEM NUMBER	DWG. NO. <b>108387-0026</b>	REV <b>B</b>
	FINISH DO NOT SCALE DRAWING		SCALE: 10:1	SIZE: C SHEET 1 OF 2

SOCKET FOR DEVICES THAT ARE WITHIN THESE SPECIFICATIONS					
Lead Count	<b>N</b>	153	Package Size	<b>D</b>	11.50
Columns	<b>ND</b>	14		<b>E</b>	13.00
Rows	<b>NE</b>	14	Ball Spacing	<b>D1</b>	13.500
Pitch	<b>e</b>	0.50		<b>E1</b>	13.500
Ball Size	<b>b</b>	0.30±0.05	Encapsulant/ Top Size	<b>D2</b>	n/a
Total Thickness	<b>A</b>	n/a		<b>E2</b>	n/a
Ball Height	<b>A1</b>	0.225 min.	Pattern Style	IRREGULAR*	
Substrate Thickness	<b>A2</b>	n/a	Perimeter Rows	3	
Top Thickness	<b>A3</b>		Center Array	n/a	
Form Tolerances					
Edge	<b>aaa</b>	0.10	Bottom	<b>ddd</b>	0.08
Substrate	<b>bbb</b>	0.10	Position	<b>eee</b>	0.15
top	<b>ccc</b>	0.10	Position	<b>fff</b>	0.05

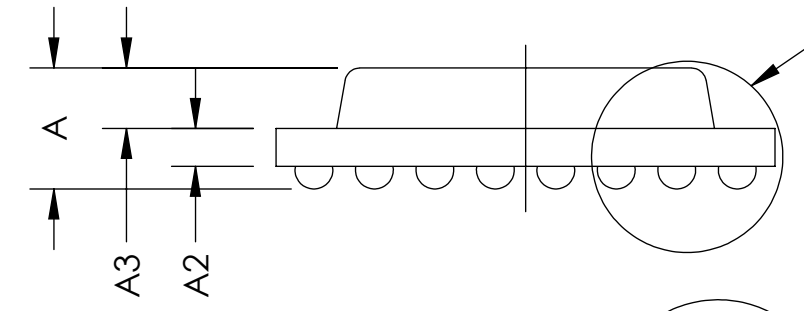
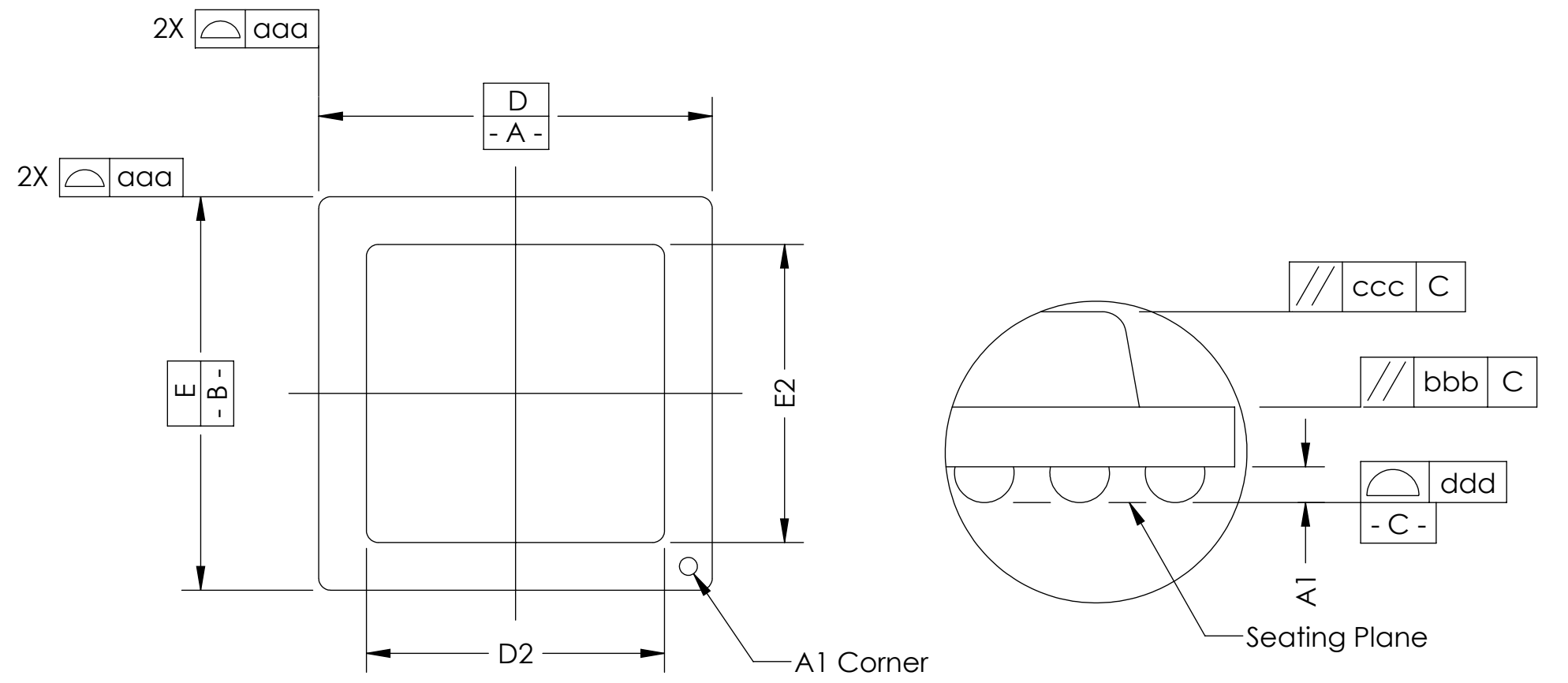
All dimensions are in millimeters.  
\* See footprint for pattern details.



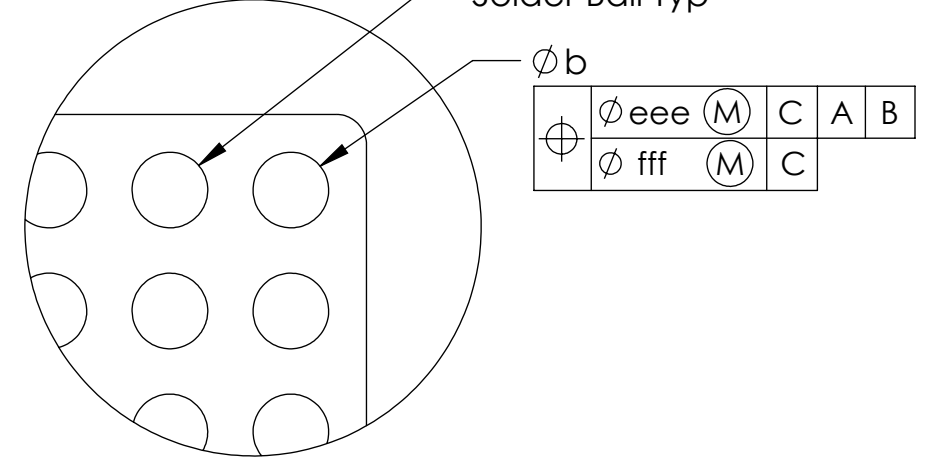
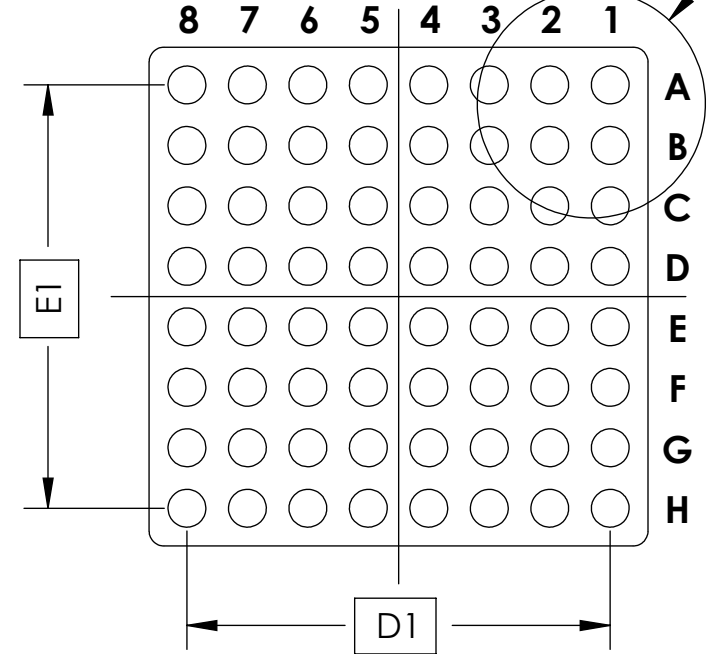
HOUSING  
107247-0026



153X CONTACT




**Detail B**



**Detail A**

**Generic Representation with Full Grid Array**

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	DRAWN	MP 11/28/2019	
LEGEND: △ NOTE CALLOUT ◻ REVISION CHANGE ○ ITEM NUMBER	CHECKED	MP 06/14/13	TITLE: SCKT, 153G4011.5X13-0.50 WITH EUTECTIC SOLDER BALLS
			DWG. NO. <b>108387-0026</b>
REV <b>B</b>			
SCALE: 5:1		SIZE: C	SHEET 2 OF 2